

General Description

The ZM027N03B combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. This device is ideal for load switch and battery protection applications.

Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

Application

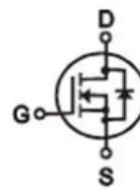
- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Ordering Information:

Part NO.	ZM027N03B
Marking	ZM027N03
Packing Information	RELL TAPE
Basic ordering unit (pcs)	800

Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$)

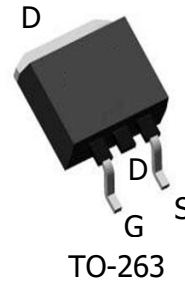
Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_D @ T_C = 25^\circ\text{C}$	130	A
	$I_D @ T_C = 75^\circ\text{C}$	98	A
	$I_D @ T_C = 100^\circ\text{C}$	82	A
Pulsed Drain Current ^①	I_{DM}	280	A
Total Power Dissipation	$P_D @ T_C = 25^\circ\text{C}$	90	W
Total Power Dissipation	$P_D @ T_A = 25^\circ\text{C}$	3.4	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 to 150	$^\circ\text{C}$
Single Pulse Avalanche Energy ($L=0.5\text{mH}, V_{GS}=10\text{V}, R_g=25\Omega, T_J=25^\circ\text{C}$)	E_{AS}	350	mJ

Product Summary


$V_{DS} = 30\text{V}$

$R_{DS(ON)} = 2.7\text{m}\Omega$

$I_D = 130\text{A}$



Single Pulse Avalanche Energy ($L=0.1\text{mH}$, $V_{GS}=10\text{V}$, $R_g=25\Omega$, $T_J=25^\circ\text{C}$)	E_{AS}	180	mJ
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Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	1.4	$^\circ\text{C/W}$
Thermal resistance, junction - ambient	R_{thJA}	-	-	36	$^\circ\text{C/W}$
Soldering temperature, wave soldering for 10s	T_{sold}	-	-	265	$^\circ\text{C}$

Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	30			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$	1.2		2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=30\text{V}$, $V_{GS}=0\text{V}$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$			± 100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS}=10\text{V}$, $I_D=24\text{A}$		2.7	3.5	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=12\text{A}$		4.6	5.5	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{DS}=25\text{V}$, $I_D=10\text{A}$		25		S
Source-drain voltage	V_{SD}	$I_S=24\text{A}$			1.28	V

Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C_{iss}	$f = 1\text{MHz}$, $V_{DS}=25\text{V}$	-	2800	-	μF
Output capacitance	C_{oss}		-	420	-	
Reverse transfer capacitance	C_{rss}		-	280	-	

Gate Charge characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Gate Resistance	R_g	$f = 1\text{MHz}$		2.5		Ω
Total gate charge	Q_g	$V_{DD} = 25\text{V}$ $I_D = 8\text{A}$ $V_{GS} = 10\text{V}$	-	27	-	nC
Gate - Source charge	Q_{gs}		-	8.6	-	
Gate - Drain charge	Q_{gd}		-	13.8	-	

Turn-ON Delay time	$t_{D(on)}$	$V_{GS}=10V, V_{DS}=15V$ $R_G = 3.3\Omega, I_D = 15A$	12	ns
Turn-ON Rise time	t_r		44	ns
Turn-Off Delay time	$t_{D(off)}$		50	ns
Turn-Off Fall time	t_f		15	ns
Reverse Recovery Time	t_{RR}	$V_{DD} = 20 V,$ $dI_S/dt = 100 A/s,$ $I_S = 30 A$	5.8	ns
Charge Time	t_a		3.4	ns
Discharge Time	t_b		2.4	ns
Reverse Recovery Charge	Q_{RR}		1.6	nC

Note: ① Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$;

Fig.1 Power Dissipation

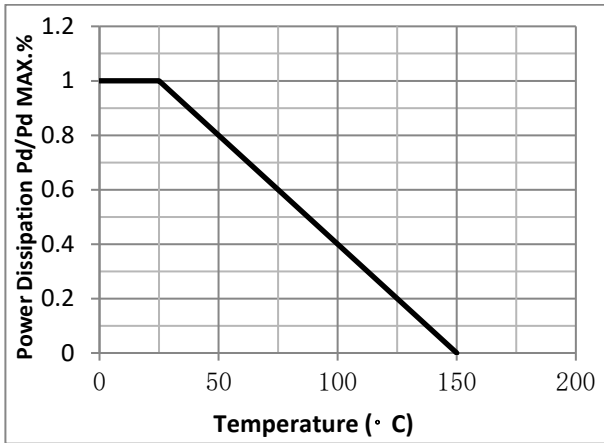


Fig.2 Typical output Characteristics

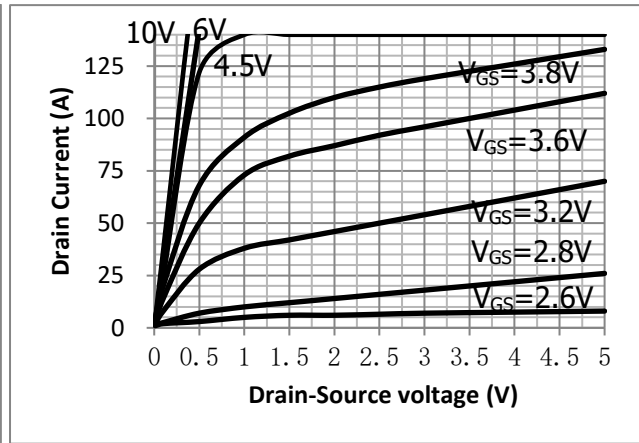


Fig.3 Threshold Voltage V.S Junction Temperature

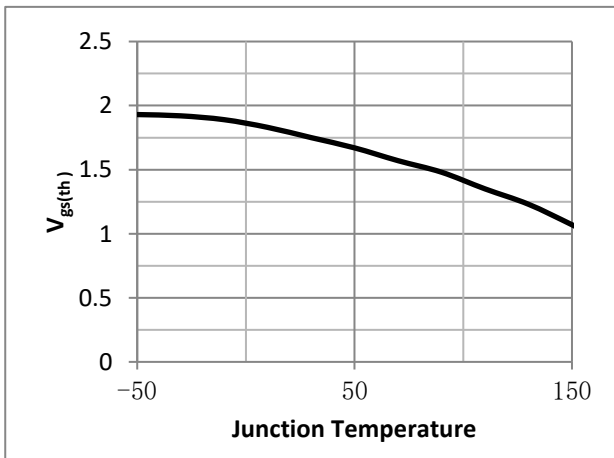


Fig.4 Resistance V.S Drain Current

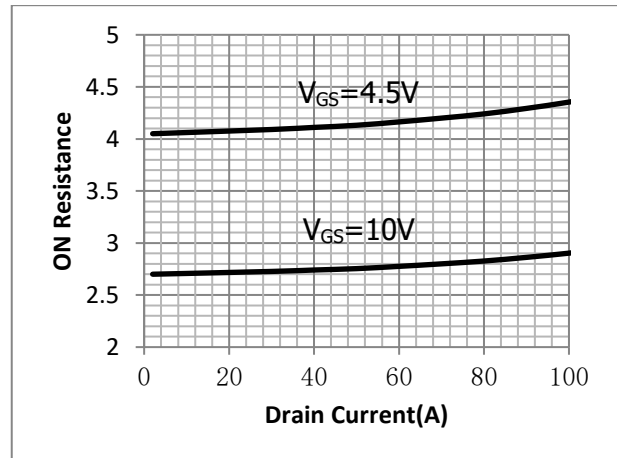


Fig.5 On-Resistance VS Gate Source Voltage

Fig.6 On-Resistance V.S Junction Temperature

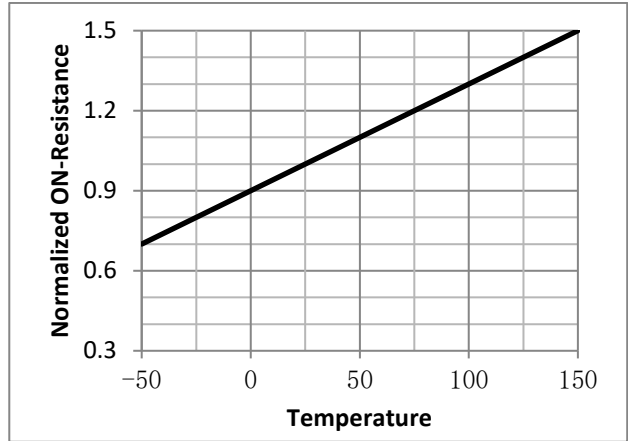
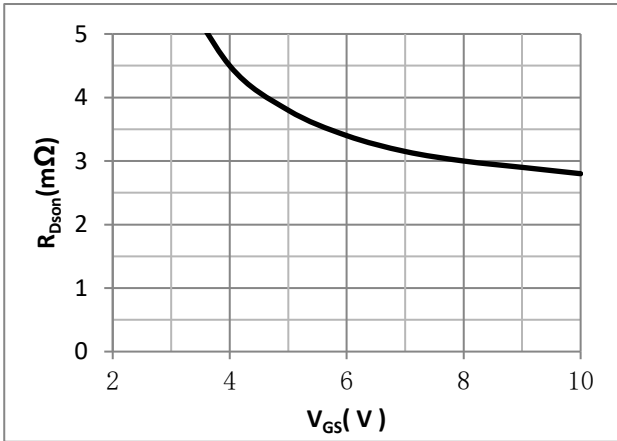


Fig.7 SOA Maximum Safe Operating Area

Fig.8 ID-Junction Temperature

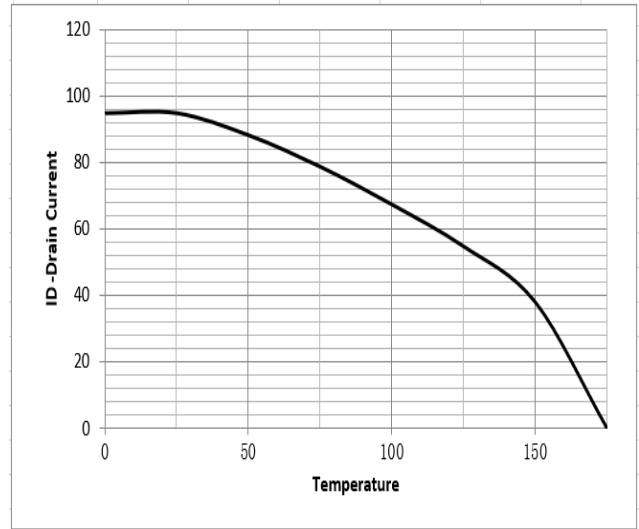
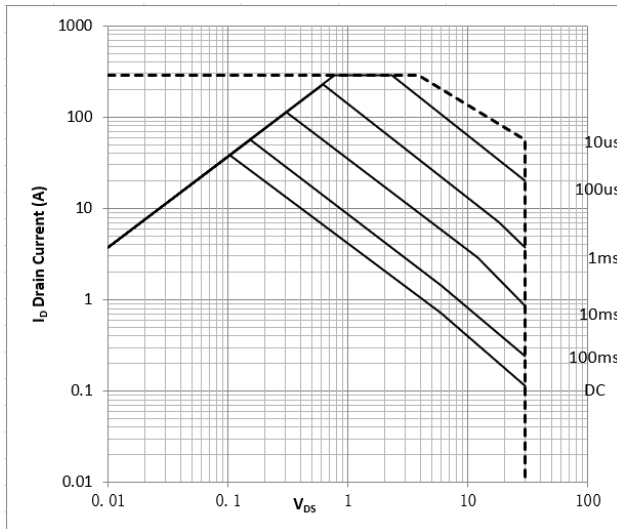


Figure 9. Diode Forward Voltage vs. Current

Figure 10. Transfer Characteristics

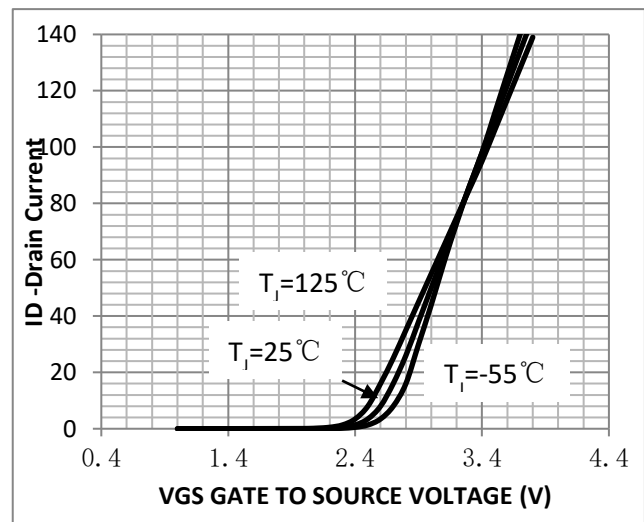
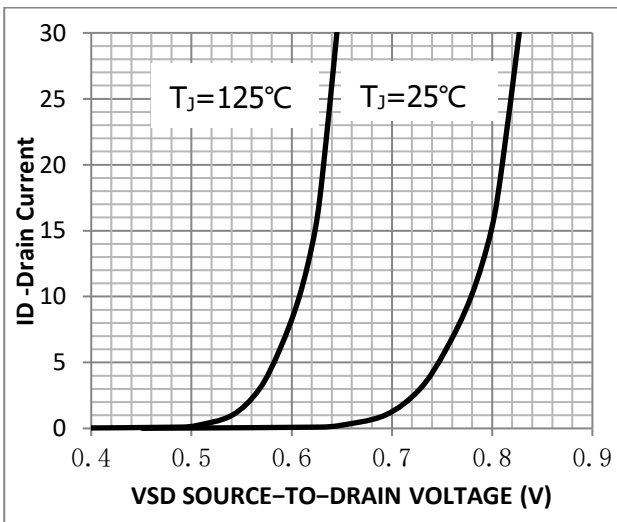


Figure 11. Gate-to-Source and

Fig.12 Capacitance Variation

Drain-to-Source Voltage vs. Total Charge

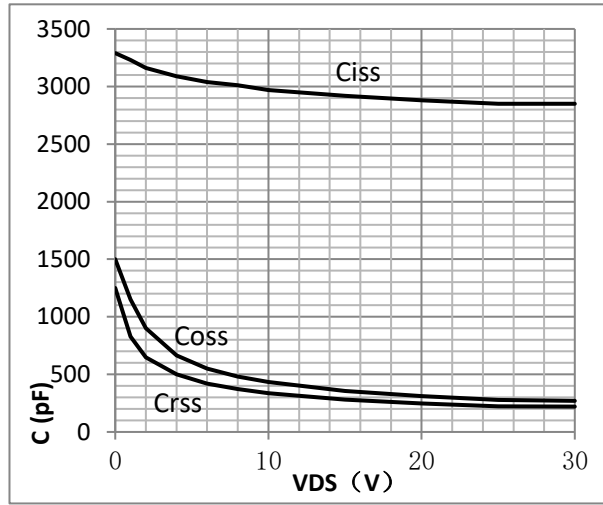
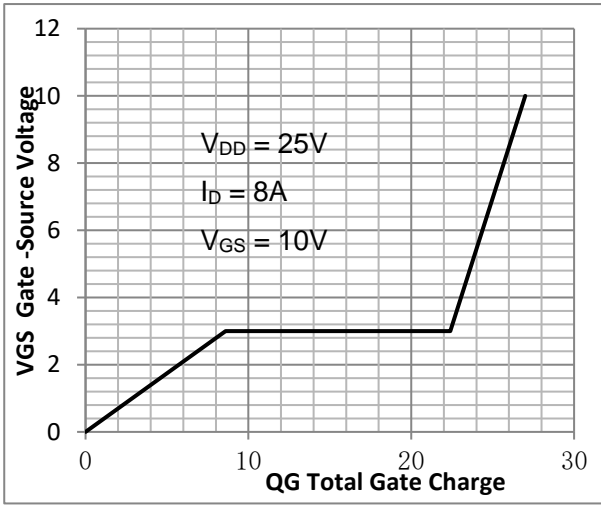


Fig.13 Switching Time Measurement Circuit

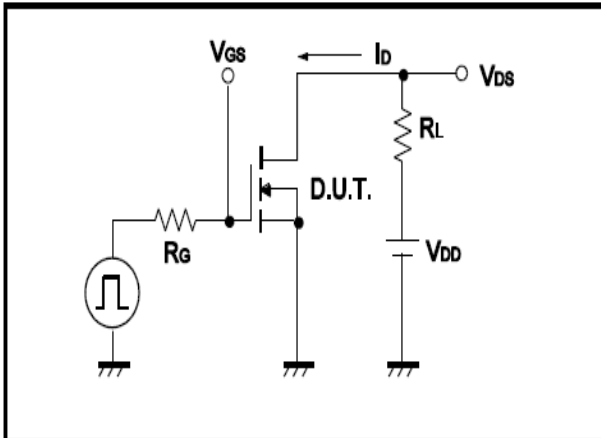


Fig.14 Gate Charge Waveform

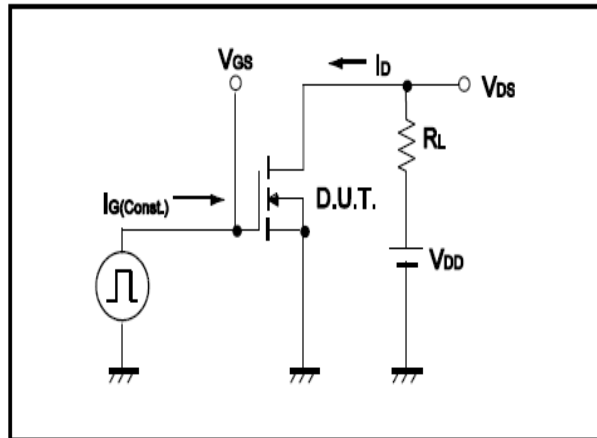


Fig.15 Avalanche Measurement Circuit

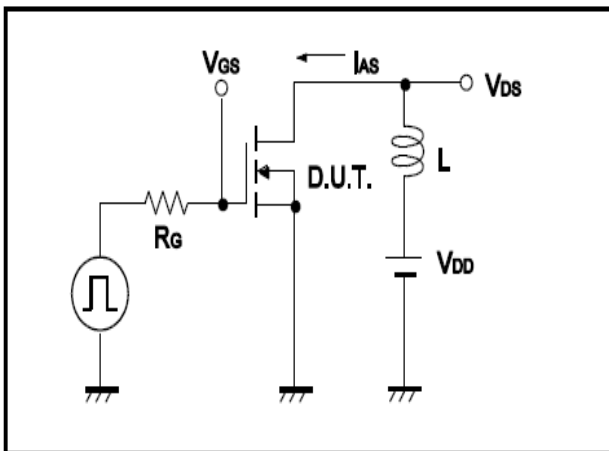


Fig.16 Avalanche Waveform

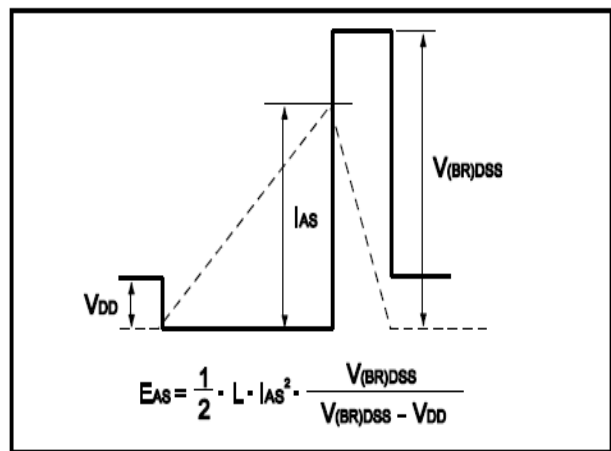
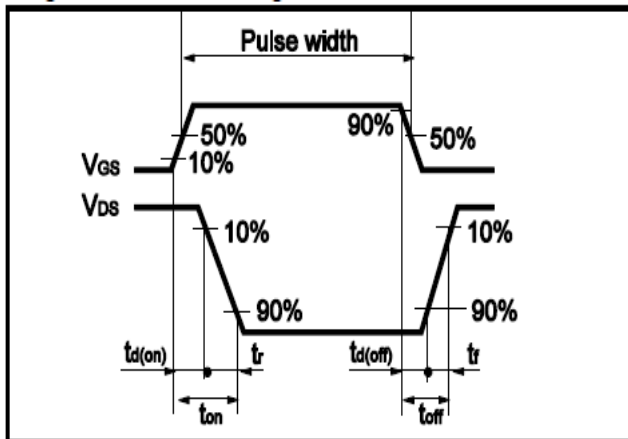


Fig.17 Gate Charge Waveform



•Dimensions (TO-263)

Unit: mm

SYMBOL	MIN	TYP	MAX	SYMBOL	MIN	TYP	MAX
A	4.42		4.72	E	8.99		9.29
B	1.22		1.32	e1	2.44		2.64
b	0.76		0.86	e2	4.98		5.18
b1	1.22		1.32	L1	15.19		15.79
b2	0.33		0.43	L2	2.29		2.79
C	1.22		1.32	L3	1.3		1.75
D	9.95		10.25				

